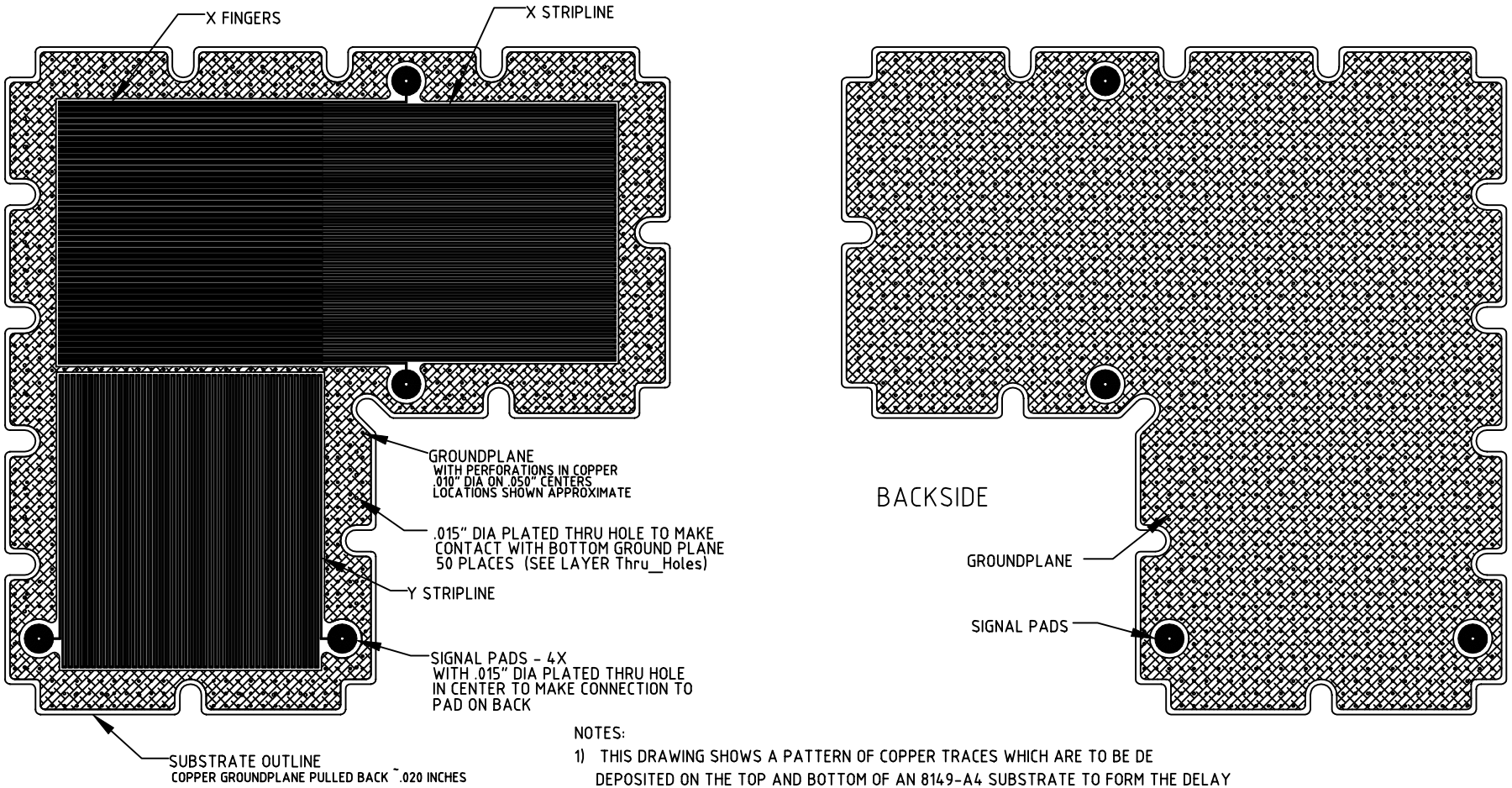
REV	DESCRIPTION	BY	DATE
A	AS FABRICATED FOR FLIGHT FUV SI SYSTEM	HDH	30SEP97

IMAGE ANODE:

SUBSTRATE IS 96% ALUMINA, .015 INCHES THICK
COPPER METALLIZATION TO BE .001 - .0015 THICK

J. Hull, 7 May 97



NOTES:

1) THIS DRAWING SHOWS A PATTERN OF COPPER TRACES WHICH ARE TO BE DE DEPOSITED ON THE TOP AND BOTTOM OF AN 8149-A4 SUBSTRATE TO FORM THE DELAY LINES AND THE X PORTION OF A CROSSED DELAY LINE DETECTOR. DRAWING 8155-A4 APPLIES THE Y PORTION OF THE DETECTOR, AND COMPLETES THE PART.
2) THE .010" DIA PERFORATIONS IN THE GROUNDS PLANES ON THE TOP AND BOTTOM ARE FOR THE CONVENIENCE OF THE VENDOR.
3) DIMENSIONAL INFORMATION IS TO BE TAKEN FROM THE FILE 8150-A4A.DXF

SUGGESTED VENDOR:

CIRQUON, INC.
1394 ST. PAUL AVE.
GURNEE. ILL 60031

PH: 847-360-1900

	REVIEWS	(NAME/DATE)
	CURRENT RELEASE	INITIAL RELEASE
CHECKED		
SYS ENGR		HDH/30SEP97

IMAGE FUV — UNIVERSITY OF CALIFORNIA AT BERKELEY SPACE SCIENCES LABORATORY

TITLE: FUV XDL ANODE FIRST LAYER FAB

ORIGINAL FILE NAME: SUB_CIRQON.DWG

DRAWN BY: J. HULL

DATE: 7 MAY, 1997

DWG NO.: 8150-A4

REV: A